

AMENDMENTS

In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Original) A porous-material-forming photo-curing resin composition comprising:
a photo-polymerizable monomer (A) having a surface tension of not more than 25×10^{-5} N/cm,
an organic compound (B) that is non-compatible with the photo-polymerizable monomer (A),
a common solvent (C) that is compatible with the photo-polymerizable monomer (A) and the organic compound (B); and
a photo-polymerization initiator (D).
2. (Original) The porous-material-forming photo-curing resin composition according to claim 1, wherein the photo-polymerizable monomer (A) is a photo-polymerizable monomer containing a fluorine atom or a silicon atom.
3. (Currently Amended) The porous-material-forming photo-curing resin composition according to claim 1 or 2, ~~wherein: the photo-polymerizable monomer (A) and~~ further comprising other photo-polymerizable monomers are used in combination and other than the photo-polymerizable monomer (A), and
wherein ~~[[the]]~~ a blending amount of the other photo-polymerizable monomers is not more than 90% by weight of the entire amount of the photo-polymerizable monomers.
4. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 3~~ claim 1 or 2, wherein the organic compound (B) is an organic compound having a surface tension of not less than 40×10^{-5} N/cm.
5. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 4~~ claim 1 or 2, wherein the component that is non-compatible with the photo-polymerizable monomer (A) is water.

6. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 5~~ claim 1 or 2, wherein the common solvent (C) is an organic solvent having a surface tension in a range from 25 to 35×10^{-5} N/cm.

7. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 6~~ claim 1 or 2, wherein the photo-polymerizable monomer (A) ~~[[has]]~~ comprises a (metha)acryloyl group or a vinyl group as a photo-polymerizable group.

8. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 7~~ claim 1 or 2, wherein the organic compound (B) comprises one or more kinds of groups and/or bonds selected from the group consisting of a hydroxide group, an amino group, a ketone bond, a sulfide bond, a sulfoxide bond and a cyclic amide bond.

9. (Currently Amended) The porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 8~~ claim 1 or 2, wherein the common solvent (C) is an aromatic or alicyclic hydrocarbon solvent, an oxygen-containing solvent or a nitrogen-containing solvent.

10. (Currently Amended) A porous resin cured product which is obtained by photo-curing the porous-material-forming photo-curing resin composition according to ~~any one of claims 1 to 9~~ claim 1 or 2.

11. (Original) The porous resin cured product according to claim 10, which is obtained by removing the organic compound (B) or water and the common solvent (C) contained therein.

12. (Currently Amended) The porous resin cured product according to claim 10 ~~or 11~~, which has a film shape or a sheet shape.

13. (Currently Amended) The porous resin cured product according to ~~any one of claims 10 to 12~~ claim 10, which has a substrate on at least one face.

14. (Currently Amended) A liquid crystal display element comprising the porous resin cured product according to ~~any one of claims 10 to 13~~ claim 10 as a supporting material.

15. (Currently Amended) A liquid crystal recording material comprising the porous resin cured product according to ~~any one of claims 10 to 13~~ claim 10 as a supporting material.

16. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the organic compound (B) is an organic compound having a surface tension of not less than 40×10^{-5} N/cm.

17. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the component that is non-compatible with the photo-polymerizable monomer (A) is water.

18. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the common solvent (C) is an organic solvent having a surface tension in a range from 25 to 35×10^{-5} N/cm.

19. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the photo-polymerizable monomer (A) [[has]] comprises a (metha)acryloyl group or a vinyl group as a photo-polymerizable group.

20. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the organic compound (B) comprises one or more kinds of groups and/or bonds selected from the group consisting of a hydroxide group, an amino group, a ketone bond, a sulfide bond, a sulfoxide bond and a cyclic amide bond.

21. (New) The porous-material-forming photo-curing resin composition according to claim 3, wherein the common solvent (C) is an aromatic or alicyclic hydrocarbon solvent, an oxygen-containing solvent or a nitrogen-containing solvent.

22. (New) A porous resin cured product which is obtained by photo-curing the porous-material-forming photo-curing resin composition according to claim 3.

23. (New) A porous resin cured product which is obtained by photo-curing the porous-material-forming photo-curing resin composition according to claim 3.